



PRODUCT SPECIFICATION

MICRO SAS RECEPTACLE

1.0 SCOPE

This Product Specification covers the performance requirements of the Micro Serial Attach SCSI / High Speed Serialized device receptacle connector.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

Product Name

Series Number

MICRO SAS RECEPTACLE, VERTICAL SMT

78832

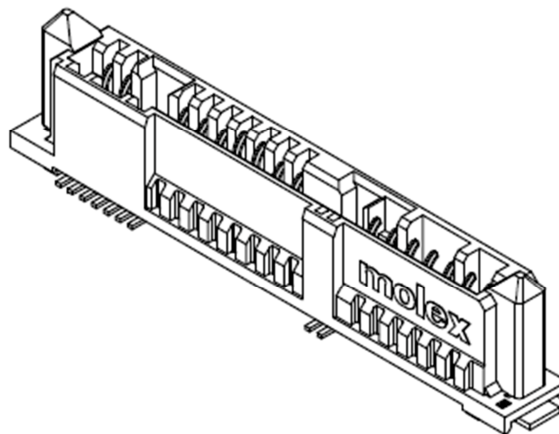
2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate Sales drawing for information on dimensions, materials, platings and markings.

2.3 SAFETY AGENCY APPROVALS

The Series 78832A in UL/ CSA Safety agency approval certifications represent the product in this product specifications.

UL FILE : E29179
CSA : 1699020 (LR19980)



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DOCUMENT NUMBER: PS-78832-001	CREATED / REVISED BY: BOKOK	CHECKED BY: MLONG	APPROVED BY: SHLENI



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3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents form a part of this specification to the extent specified herewith. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In addition, in event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

SFF-8486 Specification for Internal Serial Attachment Connector

4.0 RATINGS

4.1 VOLTAGE

30 Volts Max

4.2 CURRENT

1.5 Amps DC

4.3 TEMPERATURE

Operating: 0°C to 55°C

Non Operating: -40°C to 85°C

4.4 HUMIDITY

20% - 80%

4.5 PRESSURE

650 mm – 800 mm Hg

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5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Low Level Contact Resistance (LLCR)	Subject mated contacts assembled in housing to 20 mV maximum open circuit at 100 mA maximum. (EIA 364-23)	45 mΩ MAXIMUM [Initial] 15 mΩ MAXIMUM [Delta change from Initial]
2	Contact Current Rating (Power Segment)	<ul style="list-style-type: none"> Mount connector to a test PCB with ½ oz copper layer. Wire two adjacent pins in parallel for supply (or the minimum number required by the connector type) Wire two adjacent pins in parallel for return (or the minimum number required by the connector type) Apply a DC current of two times the current rating per contact to the supply pins, returning through the return pins. Record temperature rise when thermal equilibrium is reached. 	1.5 A per pin MAXIMUM Temperature rise shall not exceed 30 °C at any point in the connector when contacts are powered Still Air at Ambient temperature 25 °C
3	Insulation Resistance	Apply a voltage of 500 VDC for 1 minute between adjacent terminals. Measure the insulation resistance for mated and unmated connectors (EIA 364-21)	1000 MΩ MINIMUM
4	Dielectric Withstanding Voltage	Apply a voltage of 500 VAC for 1 minute between adjacent terminals of mated and unmated connectors. (EIA 364-20 Method B)	No breakdown

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5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Connector Insertion and Removal Forces	Mate and Unmate connector assemblies at a rate of 12.5 mm per minute.	Insertion force - 40 N MAXIMUM Removal force - 2.5 N MINIMUM [Initial & After 500 cycles]
6	Durability	500 cycles for backplane/blindmate application. All at a maximum rate of 200 cycles per hour. (EIA 364-09)	No Physical damage
7	Housing Slip Out Force	Apply axial pull out force on housing at a rate of 25.4 mm per minute.	50N Minimum Housing slip out force
8	Physical Shock	Subject mated connector to 30 g's half-sine shock pulses of 11 msec duration. Three shocks in each direction applied along three mutually perpendicular planes for a total of 18 shocks. (EIA 364-27 Condition H)	No Physical damage No discontinuities of 1 μ s or longer duration

5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
9	Random Vibration	Subject mated connector to 5.35 g's RMS. 30 minutes in each of the three mutually perpendicular planes. (EIA 364-28 Condition V Test letter A)	No discontinuities of 1 μ s or longer duration
10	Humidity	Subject the connector to temperature and humidity of 40°C at 90% to 95% RH for 96 hours. (EIA 364-31 Method II Test Condition A)	No Physical damage
11	Resistance to Soldering Heat	Refer to Section 9.0 for soldering profile	No damage in appearance of connector

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12	Solderability	Unmated Connector. Steam age for 8 hours \pm 15 minutes. Solder Time: 3 \pm 0.5 seconds Solder Temperature: 260 \pm 5 °C Flux type: ROL0 (JESD 22-B-102 Condition C)	95% MIN Solder coverage
13	Temperature Life	Subject mated connector to temperature life at +85 °C for 500 hours. (EIA 364-17 Method A Test Condition 3)	No Physical damage
14	Thermal Shock	Subject connector to 10 cycles between -55 °C and +85 °C. (EIA 364-32 Test Condition I)	No Physical damage
15	Mixed Flowing Gas	Subject connector to the following condition: SO ₂ gas concentration: 0.1 ppm. NO ₂ gas concentration: 0.2 ppm. H ₂ S gas concentration: 0.01 ppm. CL ₂ gas concentration: 0.01 ppm. Temperature: 30 \pm 1 °C Relative Humidity: 70 \pm 2 % Half of the samples are exposed unmated for 7 days, then mated for the remaining 7 days. The other half of the samples mated for full 14 days test period. (EIA 364-65, Class IIA)	No Physical damage

6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage.

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7.0 TEST SEQUENCES

Test Group A to E are covered by Micro SAS Specification.

Test Group →	A	B	C	D	E	F	G
Test or Examination ↓							
Examination of the connector(s)	1, 5	1, 9	1, 8	1, 8	1, 8	1	
Low Level Contact Resistance (LLCR)	2, 4	3, 7	2, 4, 6		2,5,7		
Insulation Resistance				2, 6			
Dielectric Withstanding Voltage				3, 7			
Current Rating			7				
Insertion Force		2					
Removal Force		8					
Durability	3	4 ^(a)			3 ^(a)		
Physical Shock		6					
Vibration		5					
Humidity				5			
Temperature Life			3				
Reseating (manually unplug/plug three times)			5		6		
Mixed Flowing Gas					4		
Thermal Shock				4			
Resistance to Soldering Heat						2	
Housing Slip Out Force						3	
Solderability							1

Note –

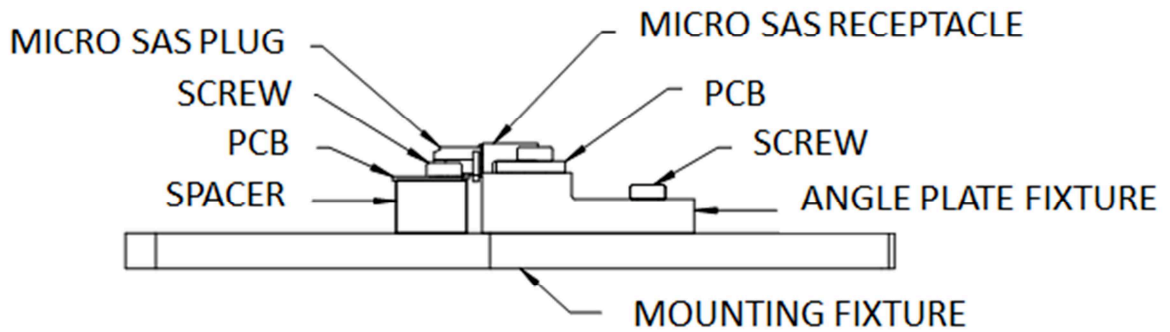
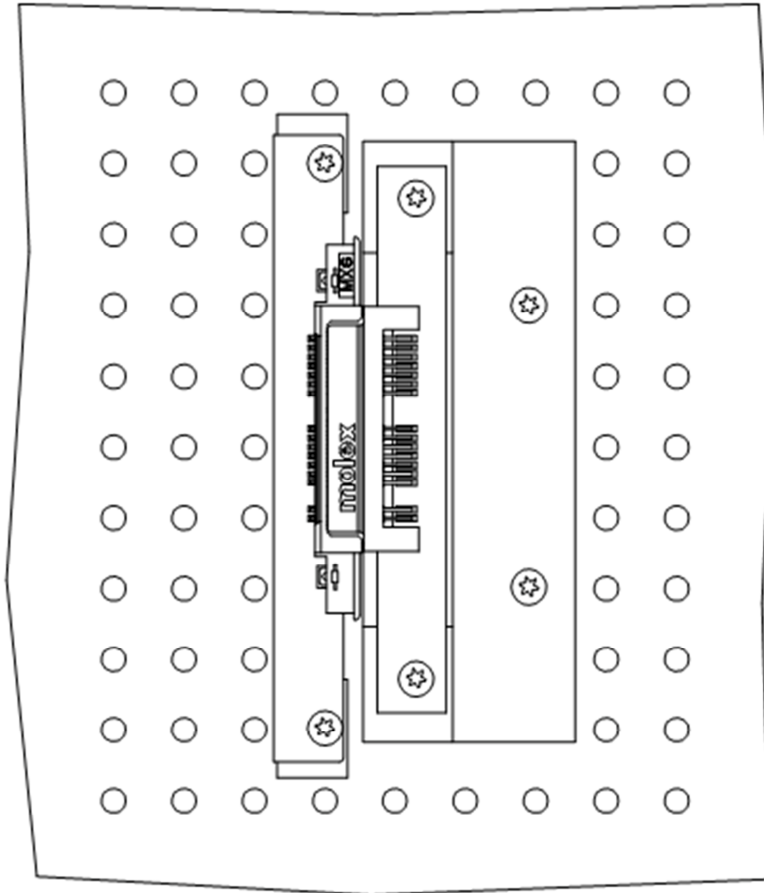
(a) Preconditioning, 50 cycles for the 500-durability cycles requirement. The insertion and removal cycle is at a maximum rate of 200 cycles per hour.

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8.0 VIBRATION/SHOCK TEST SET-UP

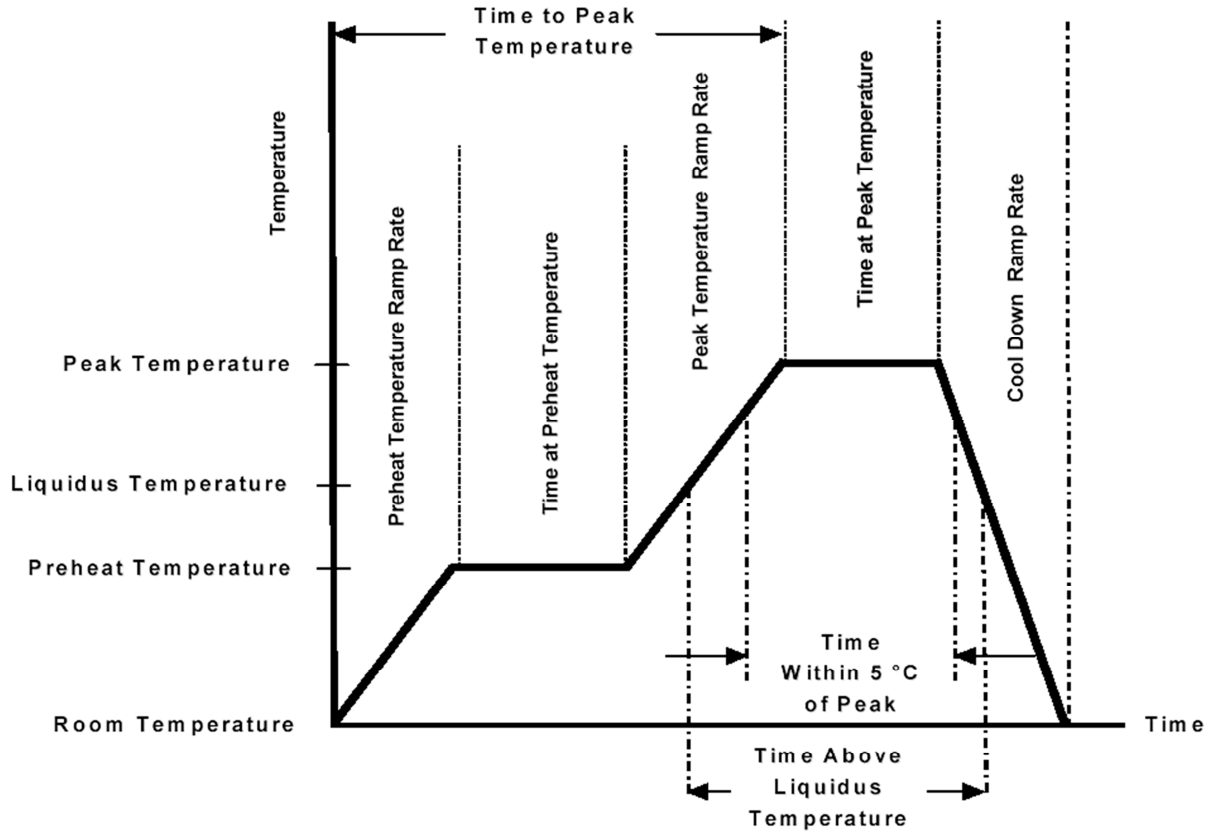


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9.0 SOLDERING PROFILE



Description	Requirement
Average Ramp Rate	3°C/sec Max
Preheat Temperature	150°C Min to 200°C Max
Preheat Time	60 to 180 sec
Ramp to Peak	3°C/sec Max
Time over Liquidus (217°C)	60 to 150 sec
Peak Temperature	260 +0/-5°C
Time within 5°C of Peak	20 to 40 sec
Ramp - Cool Down	6°C/sec Max
Time 25°C to Peak	8 min Max

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